

Merit

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This certificate is granted and awarded by the authority of the Nadcap Management Council to:

Analog Technologies Corp

*11481 Rupp Drive
Burnsville, MN 55337
United States*

This certificate demonstrates conformance and recognition of accreditation for specific services, as listed in www.eAuditNet.com on the Qualified Manufacturer's List (QML), to the revision in effect at the time of the audit for:

Electronics - Printed Board Assemblies

Certificate Number: 10484227341
Expiration Date: 30 November 2025
Accreditation Length: 18 Months



Jay Solomond
Executive Vice President & Chief Operating Officer

Performance Review Institute (PRI) | 161 Thorn Hill Road | Warrendale, PA 15086-7527

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SCOPE OF ACCREDITATION

Electronics - Printed Board Assemblies

Analog Technologies Corp
11481 Rupp Drive
Burnsville, MN 55337

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: www.eAuditNet.com - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

AC7000 Rev A - AUDIT CRITERIA FOR NADCAP ACCREDITATION

AC7120 Rev E - Nadcap Audit Criteria for Printed Board Assemblies (to be used on audits on/after 9 April 2017) (CANNOT BE COMBINED WITH AC7119 or AC7121)

- 03–Company Information (mandatory)
- 04– General (mandatory)
- 05– Outsourced Processes (mandatory)
- 06– Process Control (mandatory)
- 07– Visual Acuity (mandatory)
- 08– Customer Data (mandatory)
- 09– Electrostatic Discharge (ESD) (mandatory)
- 10– Material Management (mandatory)
- 11– Moisture Sensitive Components and Materials
- 12– Kitting
- 13.1– In–Process Verification / Inspection: General (mandatory)
- 13.2– In–Process Verification / Inspection: Visual (mandatory)
- 13.3– In–Process Verification / Inspection: AOI
- 13.4– In–Process Verification / Inspection: X–Ray
- 14.1– Secondary Assembly: Mechanical Part Installation
- 14.2– Secondary Assembly: Wire Cutting & Stripping
- 14.3– Secondary Assembly: Jumper Wire Installation
- 14.4– Secondary Assembly: Stranded Wire Tinning
- 14.5– Secondary Assembly: Compliant Pin (Press Fit) Connector Installation
- 14.6– Secondary Assembly: Bonding
- 15– Cleanliness
- 16– Final Inspection (mandatory)
- 17– Rework (mandatory)

AC7120/2 - General Soldering of Printed Board Assemblies (to be used on audits on/after 9

April 2017)

- 03– General (mandatory)
- 04– Electronic Component Preparation for Preassembly Process
- 05.1– Part Placement: General (mandatory)
- 05.2– Part Placement: Manual
- 05.3– Part Placement: Clinched Component Leads
- 06– Gold Removal
- 07– Build Through / Build Short
- 08– Hand Soldering

AC7120/3 - Plated Through Hole Technology (to be used on audits on/after 9 April 2017)

- 05– Selective Soldering

AC7120/4 - Surface Mount Technology (to be used on audits before 3 March 2019)

- 03– Preparation
- 04– Stencil Printing (mandatory)
- 05– Automated Part Placement (mandatory)
- 06– Reflow Soldering (mandatory)

AC7120/4 Rev A - Surface Mount Technology (to be used on audits on/after 3 March 2019)

- 03– Preparation
- 04– Stencil Printing (mandatory)
- 05– Automated Part Placement (mandatory)
- 06– Reflow Soldering (mandatory)

AC7120/7 Rev A - Conformal Coating of Printed Board Assemblies (to be used on audits on/AFTER 05-Nov-2023)

- 04– Material (mandatory)
- 05– Material and Equipment Compatibility (mandatory)
- 06– Preparation / Cleaning (mandatory)
- 07– Application / Drying / Curing (mandatory)
- 08– Thickness (mandatory)
- 09– Inspection (mandatory)
- 10– Rework (mandatory)
- 11– Training (mandatory)

AC7120/9 - Programming (to be used on audits on/after 9 April 2017)

- 04– General (mandatory)
- 05– Component Programming (Prior to Assembly)
- 06– Circuit Card Assembly Programming

AC7120/10 - Final Testing (to be used on audits on/after 9 April 2017)

04- General